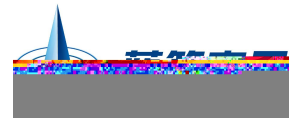


A	2020.02	ALL	SI2301 BRCS2301MA		
B	2020.03.10	1 2	1. “ ” 2.		
C	2020-5-15	1			
D	2021-12-3	3	CISS COSS CRSS		
A	2022-6-20	all	Q AEC-Q101 , H Q 245±5°C 5± 0.5sec 255± 5°C 5±0.5sec		

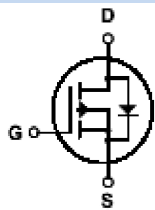


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SOT-23 塑封封装 P 道 MOS 场效应管。
P- CHANNEL MOSFET in a SOT-23 Plastic Package.

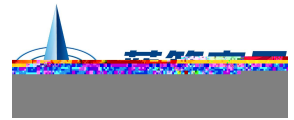
芯片采用超高密度元胞设计技术， $R_{DS(ON)}$ 导通电阻小，SOT-23 封装，符合 AEC-Q101 标准高可靠性要求，无卤产品。
Super high dense cell design for low $R_{DS(ON)}$, SOT-23 package, Qualified to AEC-Q101 Standards for High Reliability, HF Product.

主要用于显示屏驱动，满足汽车应用的严格要求。
Primarily the display screen drive applications, Meet the stringent requirements of automotive applications.



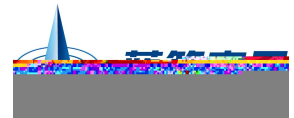
PIN1 : G PIN 2 : S PIN 3 : D

Marking	A1Q
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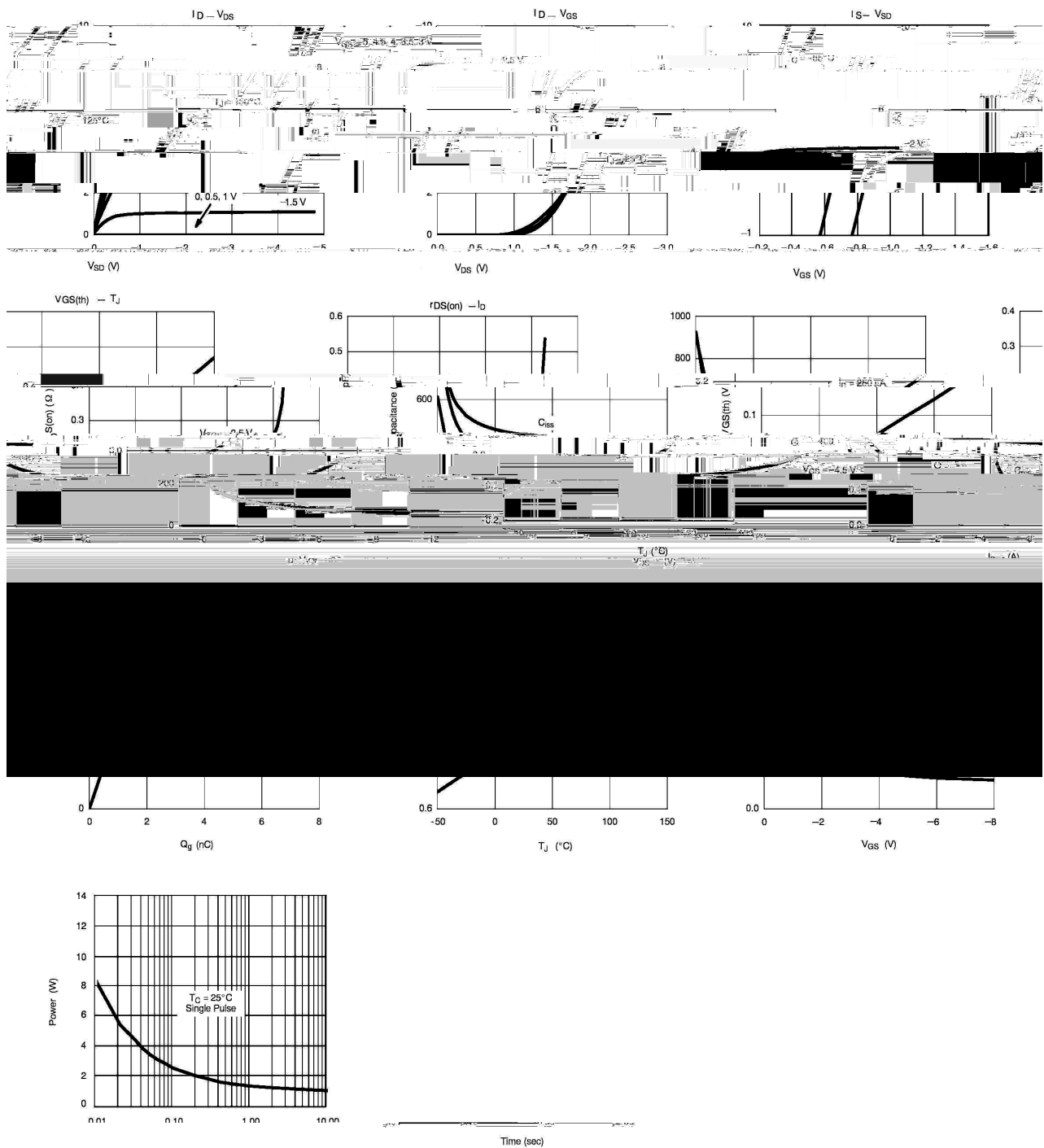


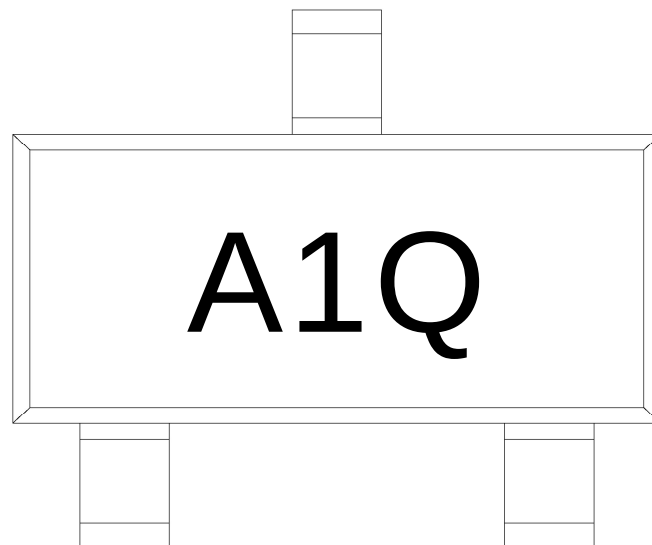
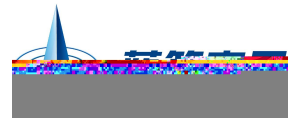
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参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Drain-Source Voltage	V_{DSS}	-20	V



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说明：

A1: 为型号代码

Q: 为汽车无卤产品标识

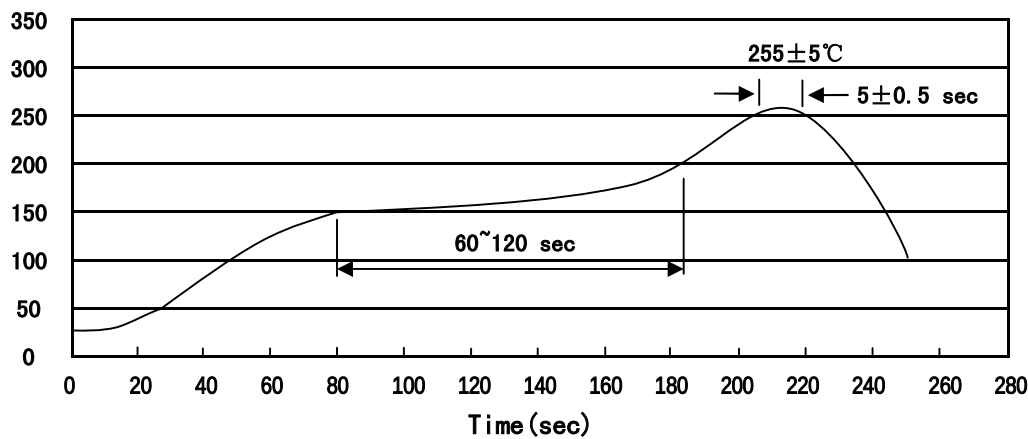
Note:

A1 : Product Type

Q: Automobile halogen-free product Code



Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|----------|-----------|---|
| 1 | 150 | 200 | 60 | 120sec; | 1.Preheating:150~200℃, Time:60~120sec. |
| 2 | 255±5 | | | 5±0.5sec; | 2.Peak Temp.:255±5℃, Duration:5±0.5sec. |
| 3 | | 2 | 10℃/sec. | | 3. Cooling Speed: 2~10℃/sec. |

260±5℃ 10±1 sec. Temp.:260±5℃ Time:10±1 sec

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box	Outer Box
SOT-23	3,000	10	30,000	6	180,000	7" ×8	180×120×180	390×385×205